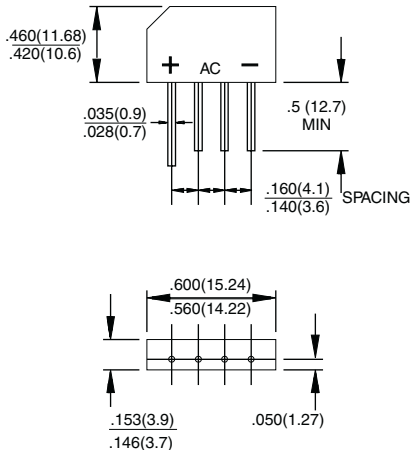


3.0 Amp. Glass Passivated Bridge Rectifiers

Dimensions in mm.	KBP	Voltage 400 V to 1000 V	Current 3.0 A
		- Glass passivated chip junction - Ideal for printed circuit board - Reliable low cost construction - High temperature soldering guaranteed: 260 °C / 10 seconds at 5 lbs., (2.3 kg) tension.	
		MECHANICAL DATA - Case: Molded plastic body. - Mounting position: Any - Leads solderable per MIL-STD-202, Method 208.	

Maximum Ratings and Electrical Characteristics at 25 °C

		KBP 304G	KBP 305G	KBP 306G	KBP 307G
V_{RRM}	Maximum Recurrent Peak Reverse Voltage (V)	400	600	800	1000
V_{RMS}	Maximum RMS Voltage (V)	280	420	560	700
V_{DC}	Maximum DC Blocking Voltage (V)	400	600	800	1000
$I_{F(AV)}$	Maximum Average Forward Rectified Current @ $T_A = 50\text{ °C}$	3.0 A			
I_{FSM}	Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC Method)	80 A			
T_j	Operating Temperature Range	-55 to +150 °C			
T_{stg}	Storage Temperature Range	-55 to +150 °C			

Electrical Characteristics at Tamb = 25 °C

V_F	Maximum Instantaneous Forward Voltage @ = 3.0 A	1.1 V
I_R	Maximum DC Reverse Current @ $T_A = 25\text{ °C}$ at Rated DC Blocking Voltage @ $T_A = 125\text{ °C}$	10.0 μ A 500 μ A
$R_{th(j-a)}$ $R_{th(j-l)}$	Typical Thermal Resistance (Note)	30°C/W 11°C/W

Notes: Thermal Resistance from Junction to Ambient and from Junction to Lead Mounted on P.C.B. with 0.4" x 0.4" (10mm x 10 mm) Copper Pads.

Rating And Characteristic Curves

FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

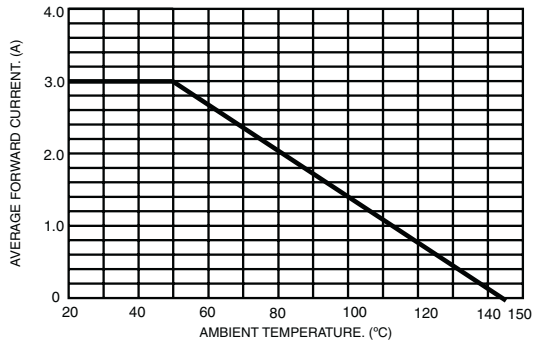


FIG.2- TYPICAL REVERSE CHARACTERISTICS PER BRIDGE ELEMENT

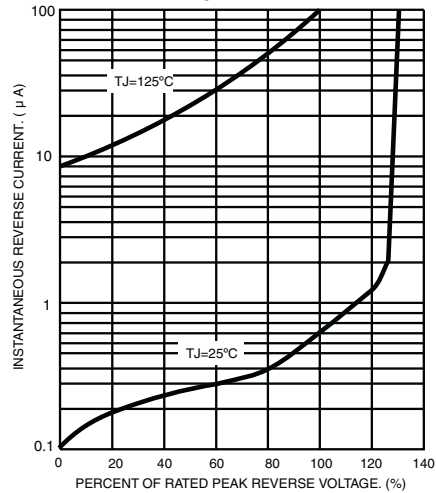


FIG.3- MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT PER BRIDGE ELEMENT

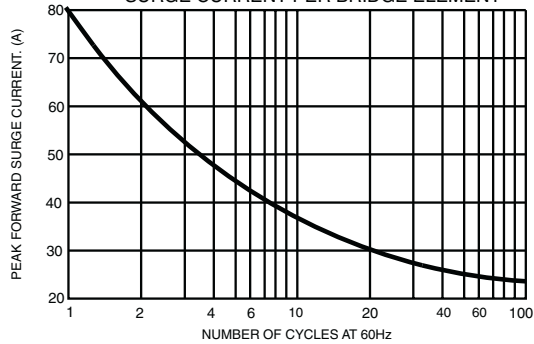


FIG.4- TYPICAL JUNCTION CAPACITANCE

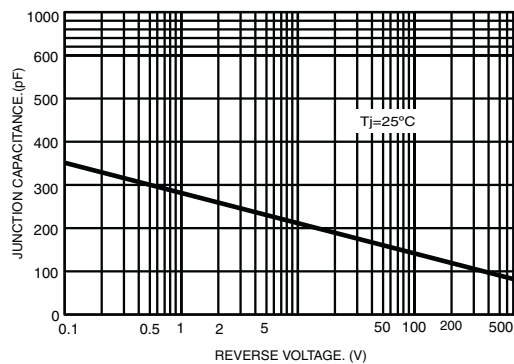


FIG.5- TYPICAL FORWARD CHARACTERISTICS PER BRIDGE ELEMENT

